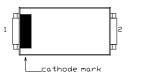
## Nihon Inter Electronics Corporation

# SBD Type: NSH03A10

#### **FEATURES**

- \* FLAT-PAK Surface Mounting Device
- \* Low Forward Voltage Drop
- \* Low Power Loss, High Efficiency
- \* High Surge Capability
- \* Packaged in 16mm Tape and Reel
- \* Not Rolling During Assembly

#### **OUTLINE DRAWING**









## Maximum Ratings

Approx Net Weight:0.16g

Rating	Symbol	NSH03A10			Unit	
Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	100			V	
Average Rectified Output Current	$I_{o}$	1.5	Ta=25°C *1	50Hz Half Sine	Α	
		3.0	Tl=112°C	Wave Resistive Load	А	
RMS Forward Current	I <sub>F(RMS)</sub>	4.71			Α	
Surge Forward Current	I <sub>FSM</sub>	60 50Hz Half Sine Wave,1cycle Non-repetitive		A		
Operating JunctionTemperature Range	$T_{jw}$	-40 to +150			°C	
Storage Temperature Range	Tstg	-40 to +150			°C	

### **Electrical** • Thermal Characteristics

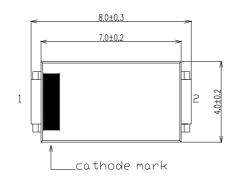
Ch	aracteristics	Symbol	pol Conditions		Тур.	Max.	Unit	
Peak Reve	Peak Reverse Current I <sub>RM</sub> Tj= 25°C, V <sub>RM</sub> = V <sub>RRM</sub>		-	-	1	mA		
Peak Forward Voltage		$V_{\mathrm{FM}}$	Tj= 25°C, I <sub>FM</sub> = 3.0A	-	-	0.85	V	
Thermal	Junction to Ambient	Rth <sub>(j-a)</sub>	Alumina Substrate Mounted *1	-	-	89	°C/W	
Resistance	Junction to Lead	Rth <sub>(j-l)</sub>	+	-	-	13	C/W	

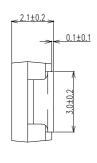
<sup>\*1</sup> Alumina Substrate Mounted (Soldering Lands=2x3.5mm,Both Sides)

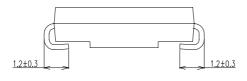
(Tl: Lead Temperature)

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## NSH03A10 OUTLINE DRAWING (Dimensions in mm)









SOLDERING PAD

